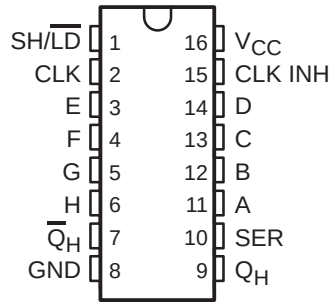


SN54HC165, SN74HC165 8-BIT PARALLEL-LOAD SHIFT REGISTERS

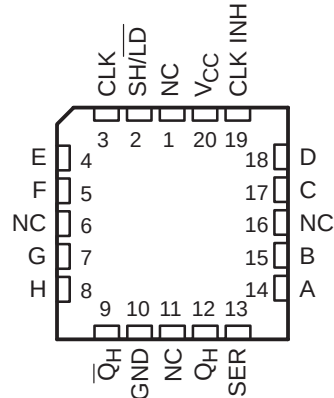
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- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 80- μ A Max I_{CC}
- Typical $t_{pd} = 13$ ns
- ± 4 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Max
- Complementary Outputs
- Direct Overriding Load (Data) Inputs
- Gated Clock Inputs
- Parallel-to-Serial Data Conversion

SN54HC165 . . . J OR W PACKAGE
SN74HC165 . . . D, DB, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54HC165 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The 'HC165 devices are 8-bit parallel-load shift registers that, when clocked, shift the data toward a serial (Q_H) output. Parallel-in access to each stage is provided by eight individual direct data (A–H) inputs that are enabled by a low level at the shift/load (SH/LD) input. The 'HC165 devices also feature a clock-inhibit (CLK INH) function and a complementary serial ($\bar{Q}_H$) output.

ORDERING INFORMATION

T_A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube of 25	SN74HC165N	SN74HC165N
	SOIC – D	Tube of 40	SN74HC165D	HC165
		Reel of 2500	SN74HC165DR	
		Reel of 250	SN74HC165DT	
	SOP – NS	Reel of 2000	SN74HC165NSR	HC165
	SSOP – DB	Reel of 2000	SN74HC165DBR	HC165
–55°C to 125°C	TSSOP – PW	Tube of 90	SN74HC165PW	HC165
		Reel of 2000	SN74HC165PWR	
		Reel of 250	SN74HC165PWT	
	CDIP – J	Tube of 25	SNJ54HC165J	SNJ54HC165J
	CFP – W	Tube of 150	SNJ54HC165W	SNJ54HC165W
	LCCC – FK	Tube of 55	SNJ54HC165FK	SNJ54HC165FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

SN54HC165, SN74HC165

8-BIT PARALLEL-LOAD SHIFT REGISTERS

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description/ordering information (continued)

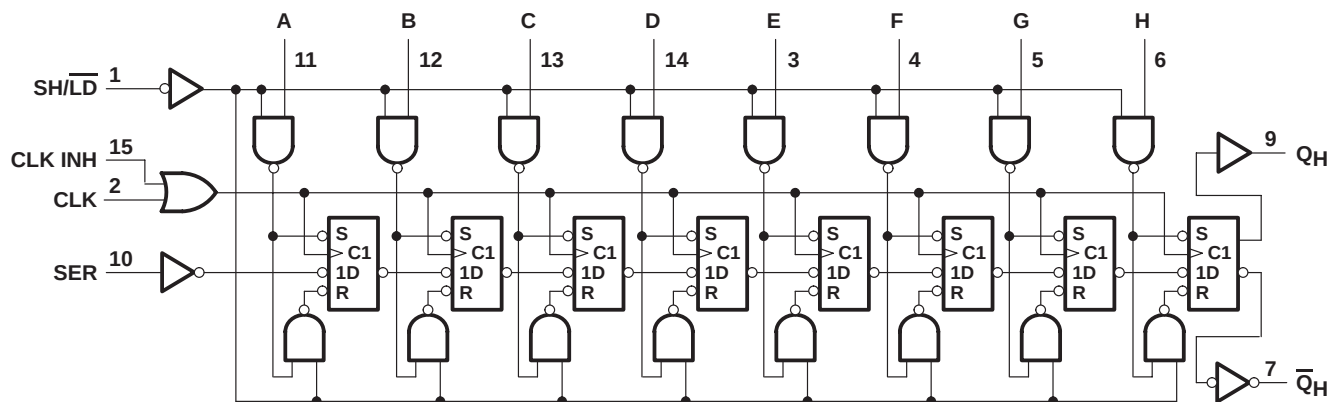
Clocking is accomplished by a low-to-high transition of the clock (CLK) input while $\overline{\text{SH/LD}}$ is held high and CLK INH is held low. The functions of CLK and CLK INH are interchangeable. Since a low CLK and a low-to-high transition of CLK INH also accomplish clocking, CLK INH should be changed to the high level only while CLK is high. Parallel loading is inhibited when $\overline{\text{SH/LD}}$ is held high. While $\overline{\text{SH/LD}}$ is low, the parallel inputs to the register are enabled independently of the levels of the CLK, CLK INH, or serial (SER) inputs.

FUNCTION TABLE

INPUTS			FUNCTION
$\overline{\text{SH/LD}}$	CLK	CLK INH	
L	X	X	Parallel load
H	H	X	No change
H	X	H	No change
H	L	$\uparrow$	Shift [†]
H	$\uparrow$	L	Shift [†]

[†] Shift = content of each internal register shifts toward serial output Q_H . Data at SER is shifted into the first register.

logic diagram (positive logic)

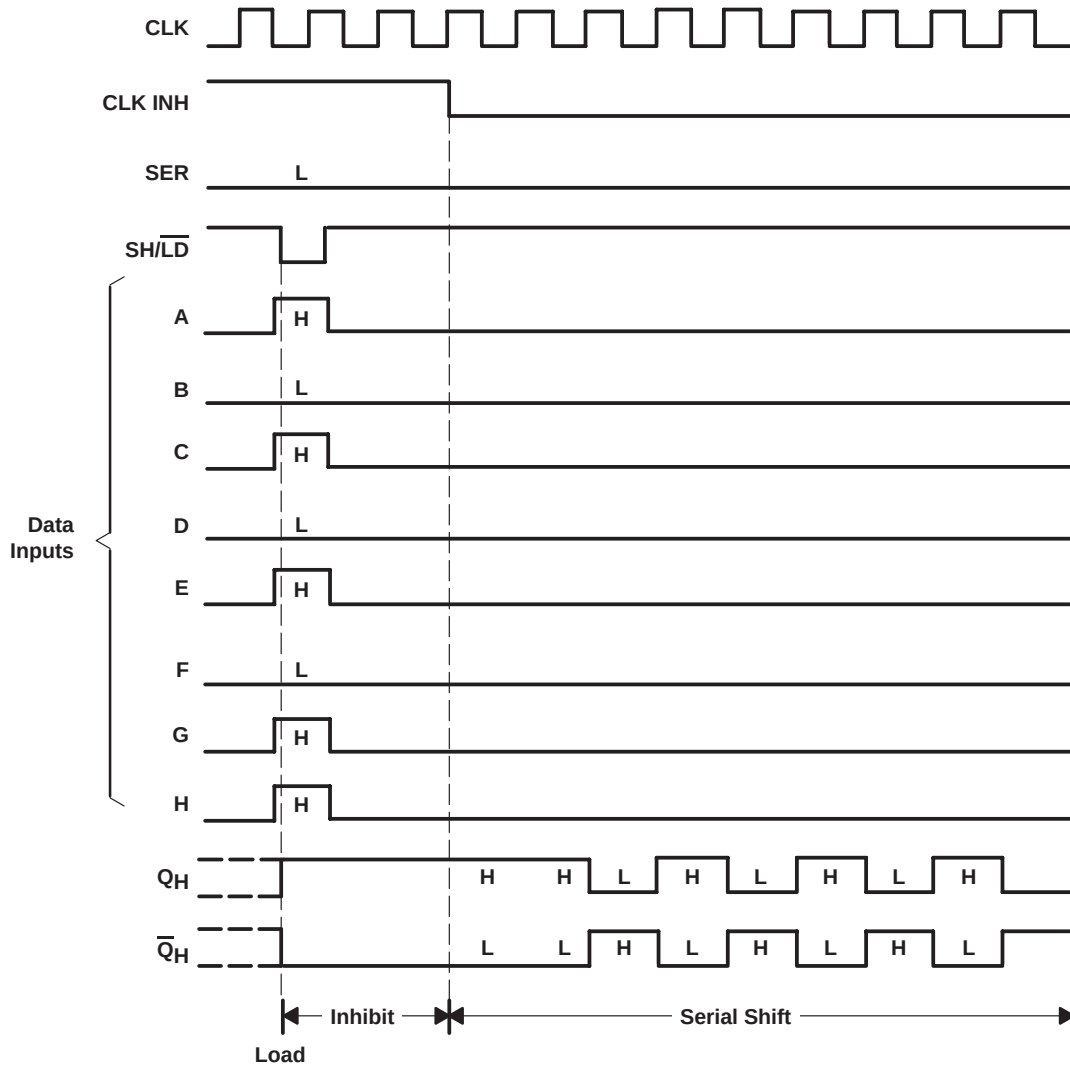


Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

SN54HC165, SN74HC165 8-BIT PARALLEL-LOAD SHIFT REGISTERS

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typical shift, load, and inhibit sequence



SN54HC165, SN74HC165

8-BIT PARALLEL-LOAD SHIFT REGISTERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC}	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Note 1)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±25 mA
Continuous current through V_{CC} or GND	±50 mA
Package thermal impedance, θ_{JA} (see Note 2): D package	73°C/W
DB package	82°C/W
N package	67°C/W
NS package	64°C/W
PW package	108°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN54HC165			SN74HC165			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage		2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5			1.5			V
		V _{CC} = 4.5 V	3.15			3.15			
		V _{CC} = 6 V	4.2			4.2			
V _{IL}	Low-level input voltage	V _{CC} = 2 V	0.5			0.5			V
		V _{CC} = 4.5 V	1.35			1.35			
		V _{CC} = 6 V	1.8			1.8			
V _I	Input voltage		0	V _{CC}		0	V _{CC}		V
V _O	Output voltage		0	V _{CC}		0	V _{CC}		V
Δt/Δv [‡]	Input transition rise/fall time	V _{CC} = 2 V	1000			1000			ns
		V _{CC} = 4.5 V	500			500			
		V _{CC} = 6 V	400			400			
T _A	Operating free-air temperature		−55	125		−40	85		°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

[‡] If this device is used in the threshold region (from $V_{ILmax} = 0.5$ V to $V_{IHmin} = 1.5$ V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at $t_t = 1000$ ns and $V_{CC} = 2$ V does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.

SN54HC165, SN74HC165 8-BIT PARALLEL-LOAD SHIFT REGISTERS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{CC}	T _A = 25°C			SN54HC165		SN74HC165		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = -20 µA	2 V	1.9	1.998		1.9		1.9		V
			4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
		I _{OH} = -4 mA	4.5 V	3.98	4.3		3.7		3.84		
		I _{OH} = -5.2 mA	6 V	5.48	5.8		5.2		5.34		
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 20 µA	2 V		0.002	0.1		0.1		0.1	V
			4.5 V		0.001	0.1		0.1		0.1	
			6 V		0.001	0.1		0.1		0.1	
		I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		I _{OL} = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
I _I	V _I = V _{CC} or 0		6 V		±0.1	±100		±1000		±1000	nA
I _{CC}	V _I = V _{CC} or 0, I _O = 0		6 V			8		160		80	µA
C _i			2 V to 6 V		3	10		10		10	pF



SN54HC165, SN74HC165

8-BIT PARALLEL-LOAD SHIFT REGISTERS

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timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		V _{CC}	T _A = 25°C		SN54HC165		SN74HC165		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	2 V		6		4.2		5	MHz
		4.5 V		31		21		25	
		6 V		36		25		29	
t _w	SH/ $\overline{\text{LD}}$ low	2 V	80		120		100		ns
		4.5 V	16		24		20		
		6 V	14		20		17		
	CLK high or low	2 V	80		120		100		
		4.5 V	16		24		20		
		6 V	14		20		17		
t _{su}	SH/ $\overline{\text{LD}}$ high before CLK↑	2 V	80		120		100		ns
		4.5 V	16		24		20		
		6 V	14		20		17		
	SER before CLK↑	2 V	40		60		50		
		4.5 V	8		12		10		
		6 V	7		10		9		
	CLK INH low before CLK↑	2 V	100		150		125		
		4.5 V	20		30		25		
		6 V	17		25		21		
	CLK INH high before CLK↑	2 V	40		60		50		
		4.5 V	8		12		10		
		6 V	7		10		9		
	Data before SH/ $\overline{\text{LD}}$ ↓	2 V	100		150		125		
		4.5 V	20		30		25		
		6 V	17		26		21		
t _h	SER data after CLK↑	2 V	5		5		5		ns
		4.5 V	5		5		5		
		6 V	5		5		5		
	PAR data after SH/ $\overline{\text{LD}}$ ↓	2 V	5		5		5		
		4.5 V	5		5		5		
		6 V	5		5		5		

SN54HC165, SN74HC165 8-BIT PARALLEL-LOAD SHIFT REGISTERS

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switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC165		SN74HC165		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$f_{\max}$			2 V	6	13		4.2		5		MHz
			4.5 V	31	50		21		25		
			6 V	36	62		25		29		
t_{pd}	SH/ $\overline{\text{LD}}$	Q_H or $\overline{Q}_H$	2 V		80	150		225		190	ns
			4.5 V		20	30		45		38	
			6 V		16	26		38		32	
	CLK	Q_H or $\overline{Q}_H$	2 V		75	150		225		190	
			4.5 V		15	30		45		38	
			6 V		13	26		38		32	
	H	Q_H or $\overline{Q}_H$	2 V		75	150		225		190	
			4.5 V		15	30		45		38	
			6 V		13	26		38		32	
t_t		Any	2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

operating characteristics, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	No load	75	pF

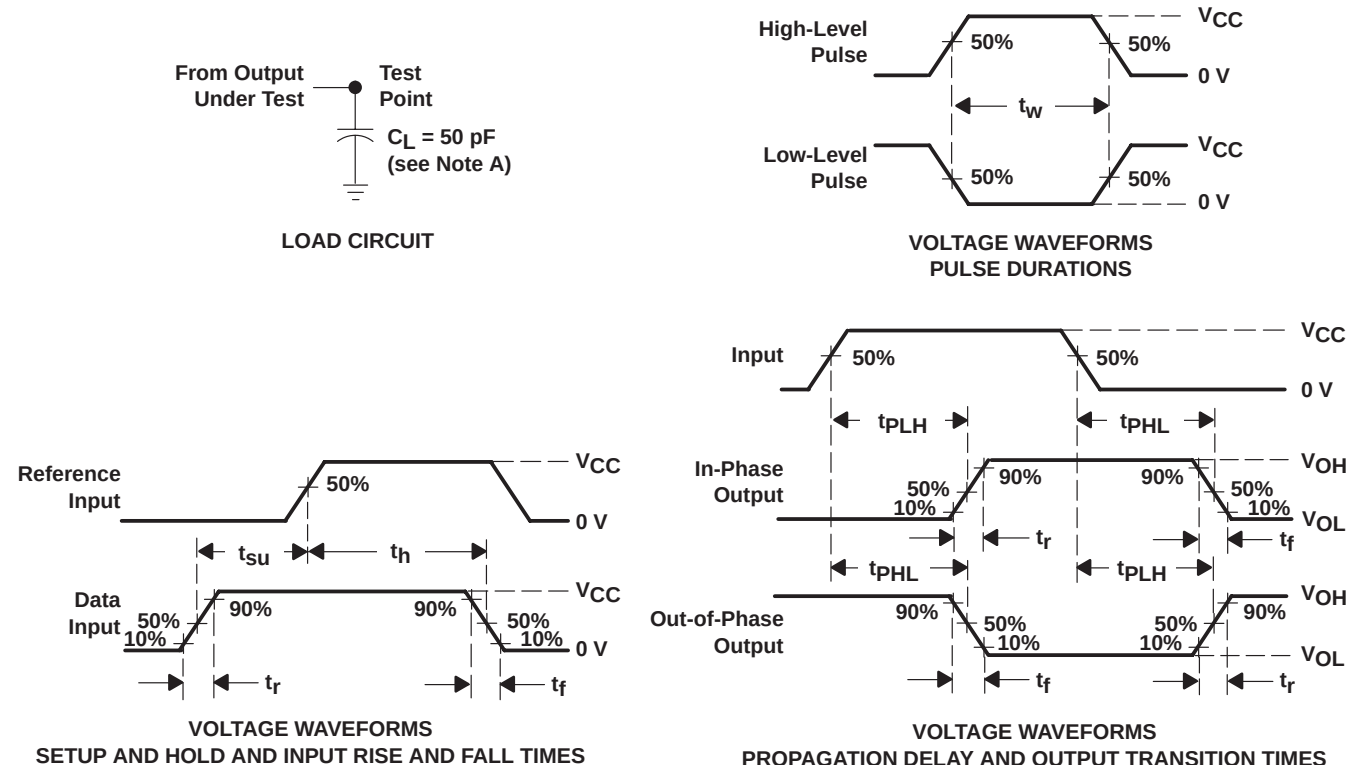


SN54HC165, SN74HC165

8-BIT PARALLEL-LOAD SHIFT REGISTERS

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PARAMETER MEASUREMENT INFORMATION



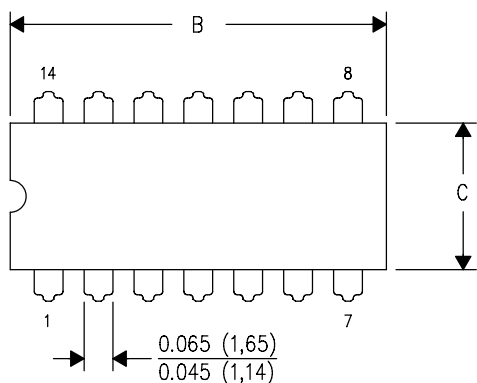
- NOTES:
- C_L includes probe and test-fixture capacitance.
 - Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 6 \text{ ns}$, $t_f = 6 \text{ ns}$.
 - For clock inputs, f_{max} is measured when the input duty cycle is 50%.
 - The outputs are measured one at a time with one input transition per measurement.
 - t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

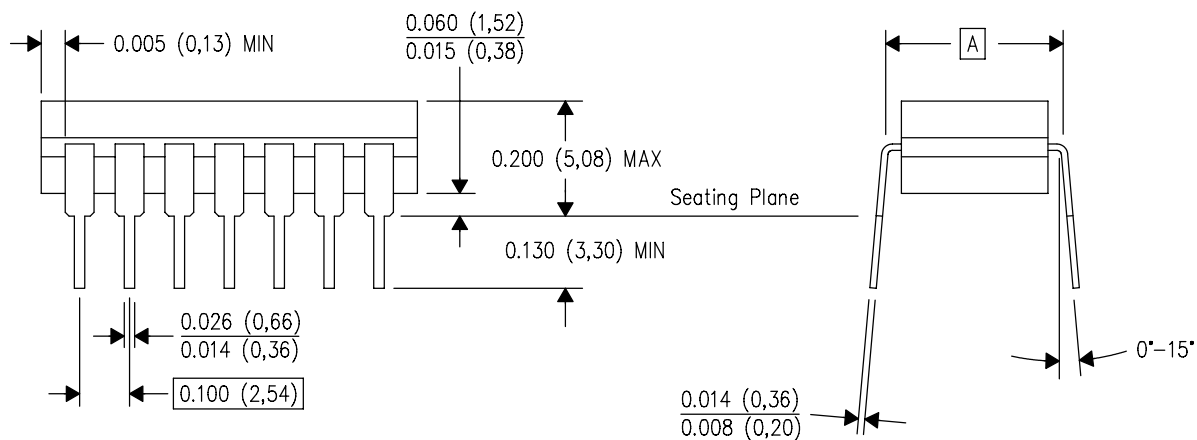
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

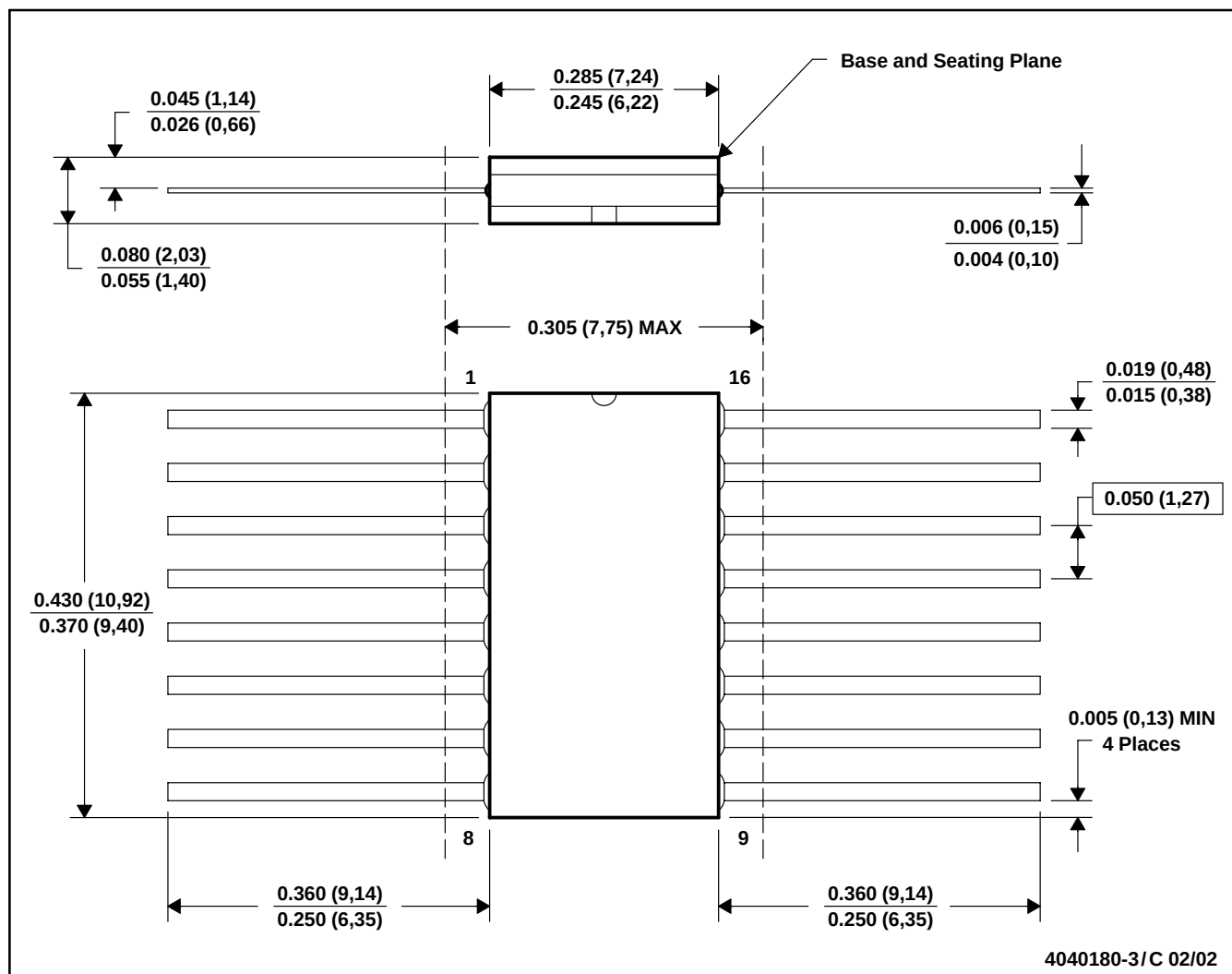


4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK

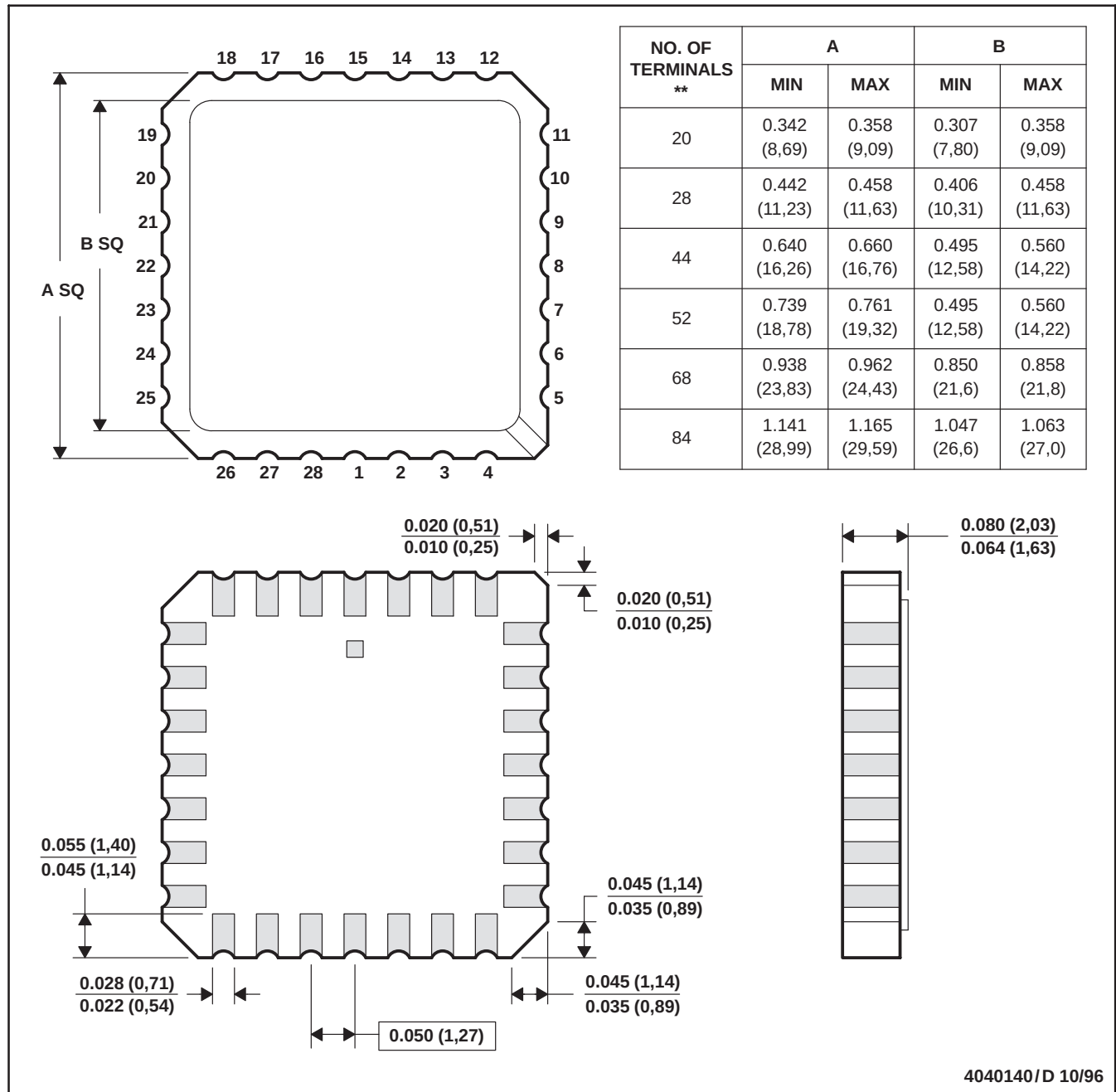


- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification only.
 E. Falls within MIL STD 1835 GDFP-1F16 and JEDEC MO-092AC

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

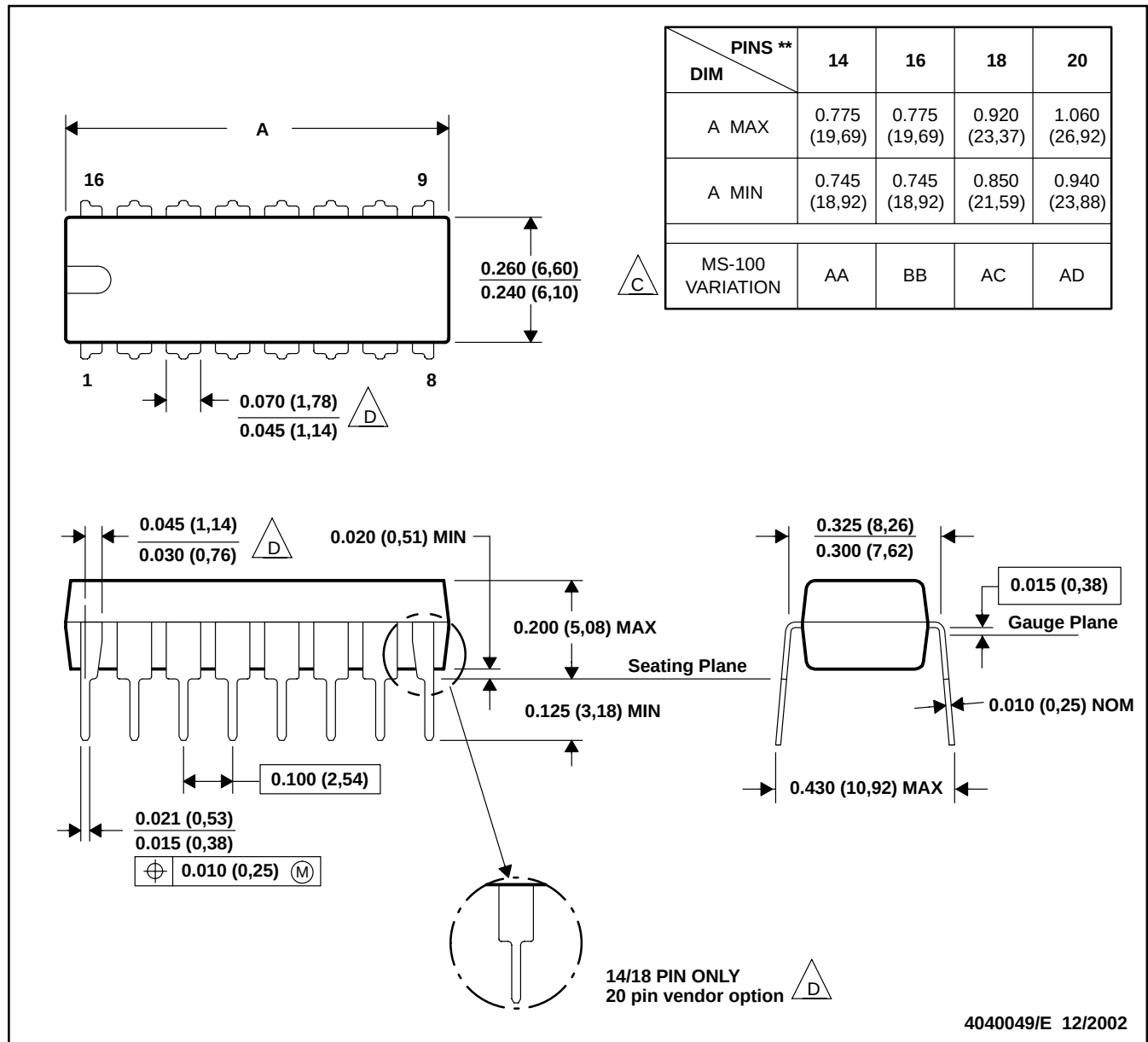


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a metal lid.
 - The terminals are gold plated.
 - Falls within JEDEC MS-004

N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

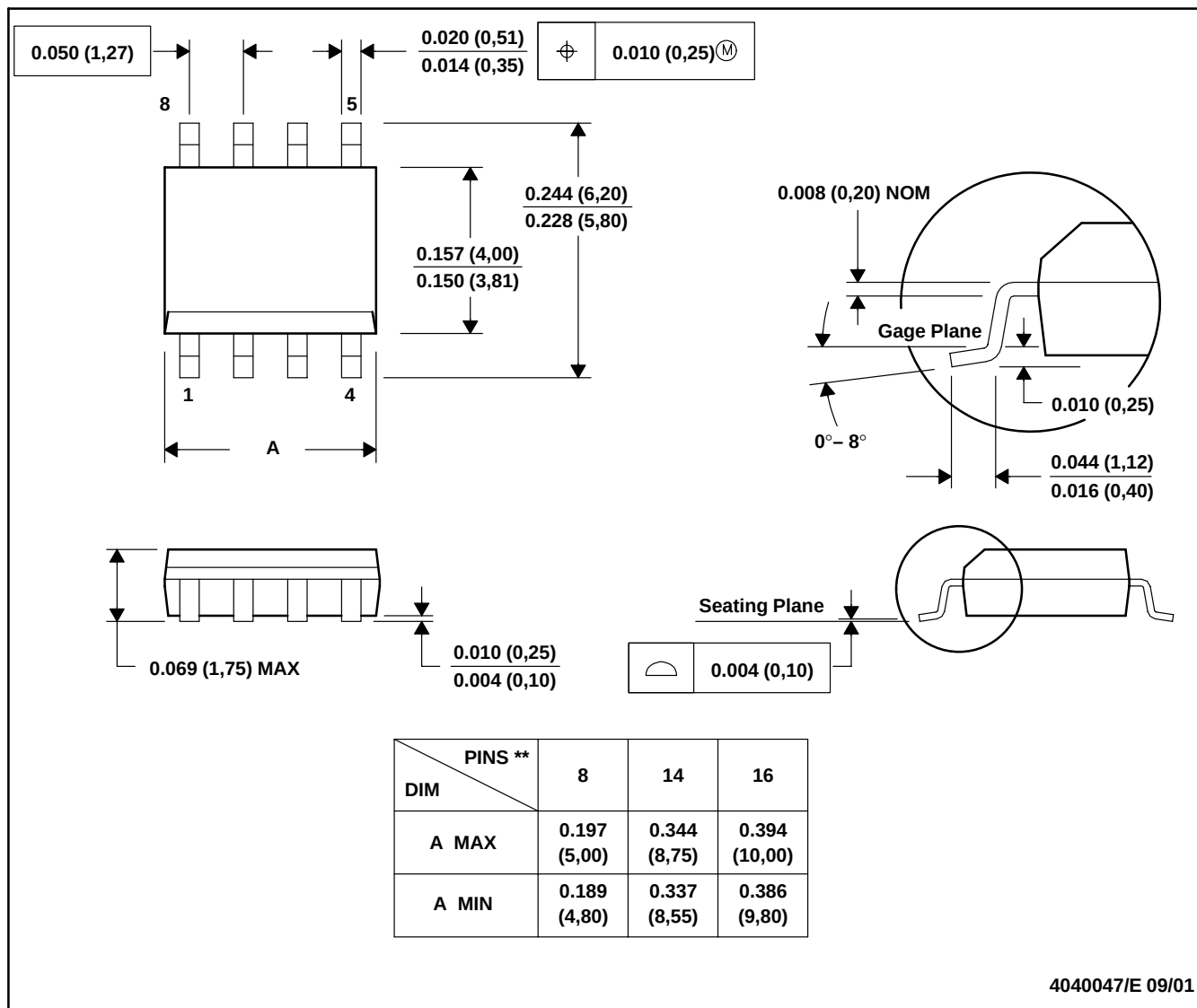
C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

D The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

8 PINS SHOWN



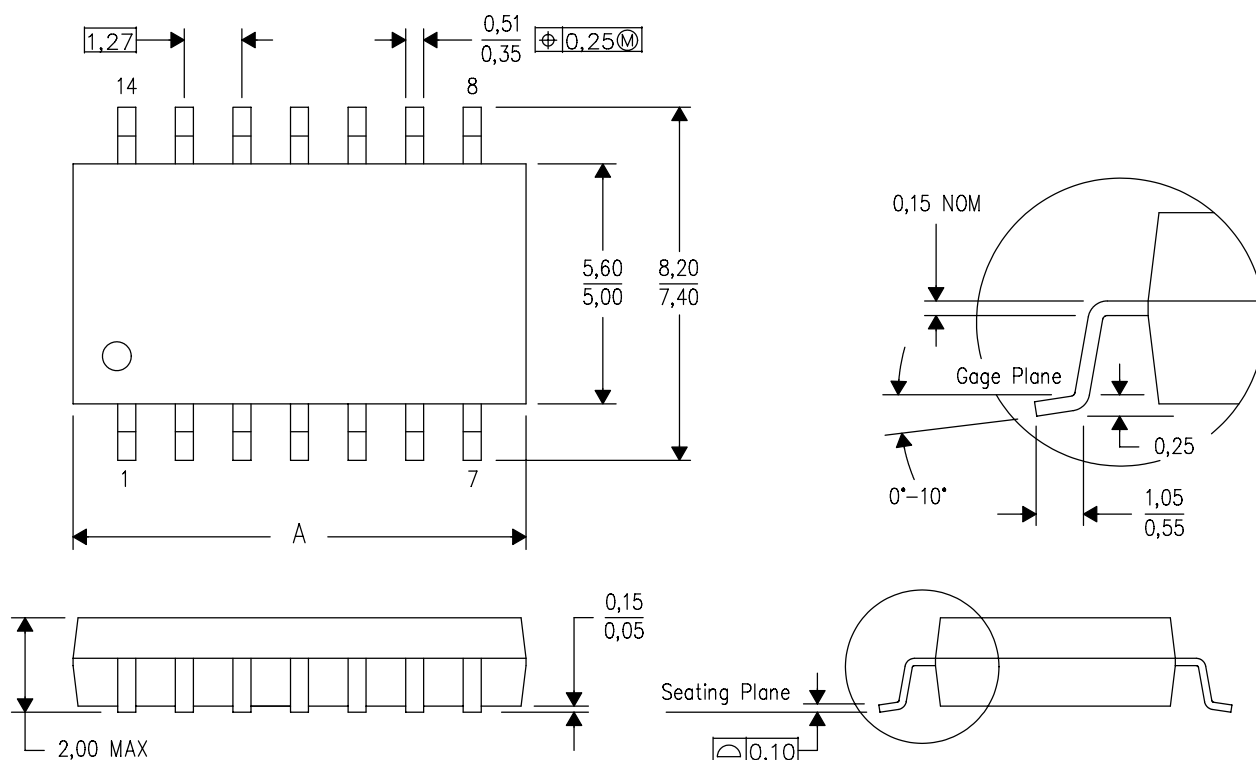
- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-012

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

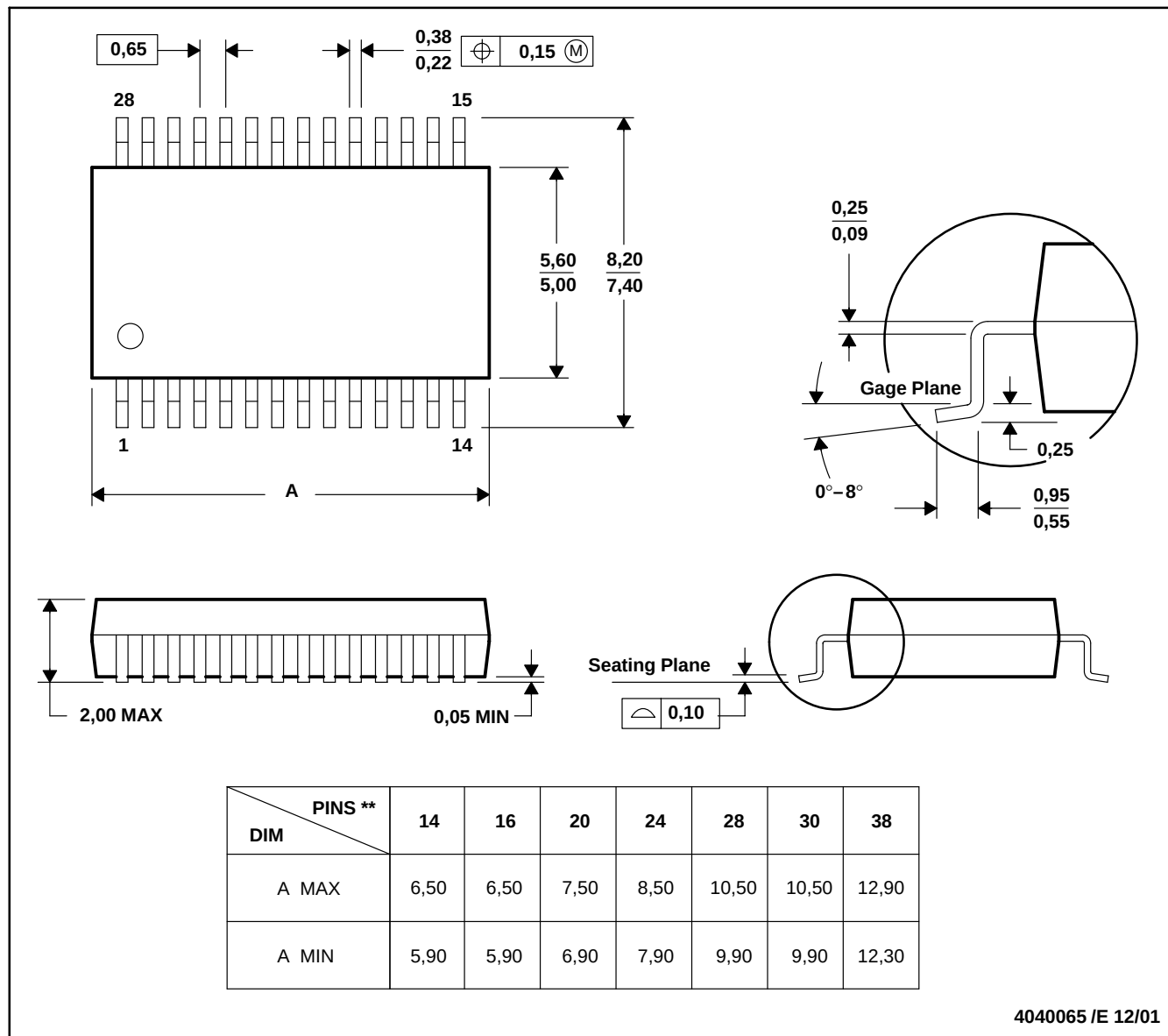
4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN

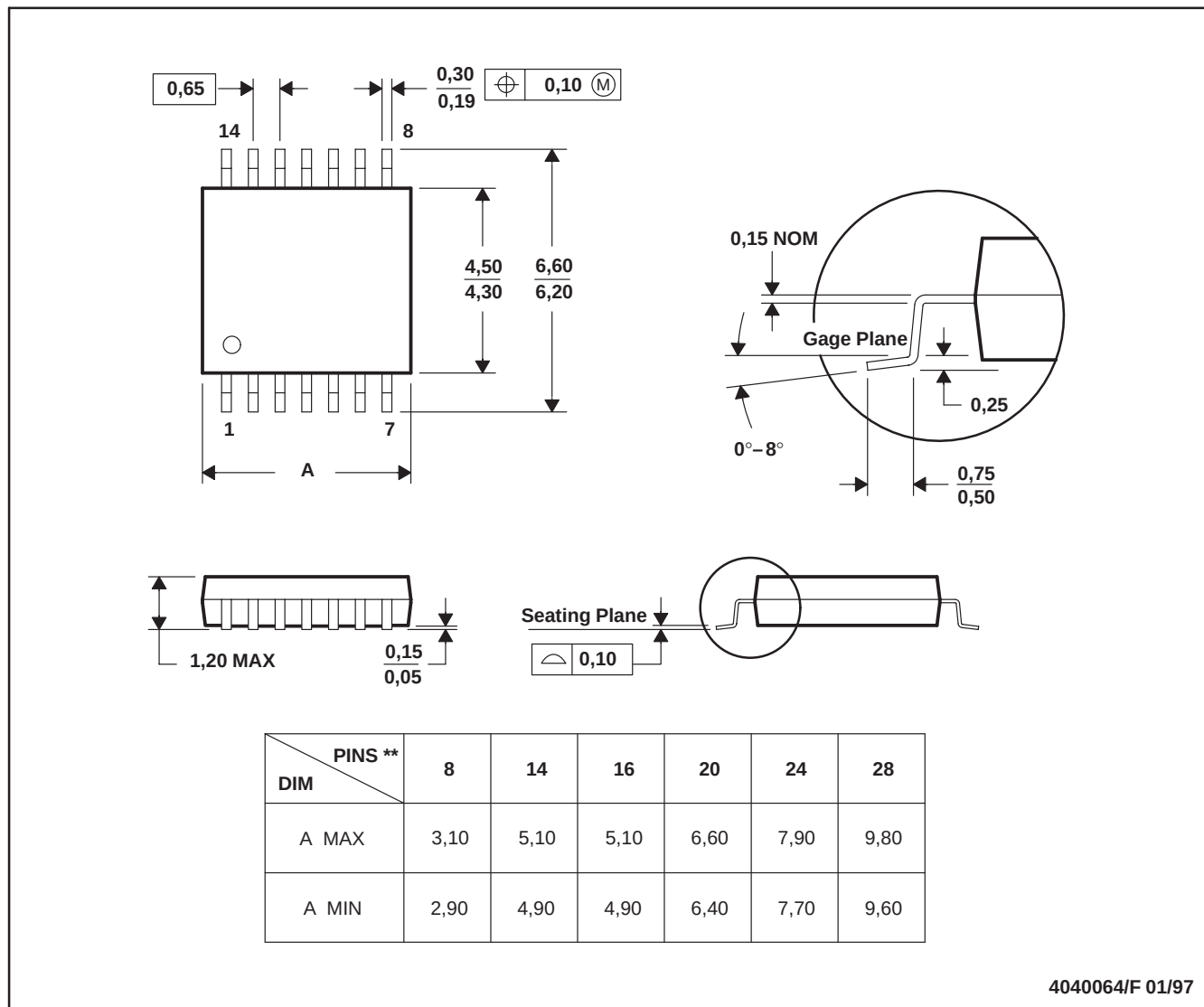


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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